JU12 HEC' OPUI/PTC 28 SEP 2005 Sheet 1 of 1

Form PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE					ATTY. DOCKET NO. AOK-05-1361		SERIA 10/550902			
					APPLICANTS					
				Shyusei Ohya et al.						
LIST OF PUBLICATIONS CITED BY APPLICANT (Use several sheets if necessary)					FILING DATE 9 28 05 GROUP 1793					
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INITIAL*		DOCUMENT NUMBER	DATE	NA	ME	CLASS	SUBCLASS	IF APPROPRIATE		
/LH/	AA	US 2002/0146615 A1	10/10/02	Kiy	oshi Yamaura et al.					
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AR E.G. Chen et al., A STEM STUDY OF A PLATINUM DEPOSIT ON AN AMORPHOUS CARBON FILM: THE EFFECTS OF CONTA										
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EXAMINER /Patricia Hailey/					DATE CONSIDERED 01/08/2008					
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